



MB1-130-01-F-S-01-SL

MB1-130-01-F-S-01-SL-N

(1.00 mm) .0394"

MB1 SERIES

MINI EDGE CARD SOCKET WITH GUIDES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn or Au over
50 μ " (1.27 μ m) Ni

Current Rating:

2.4 A per pin
(2 pins powered)

Voltage Rating:

250 VDC/354 VDC

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(5.26 mm) .207" to

(6.10 mm) .240"

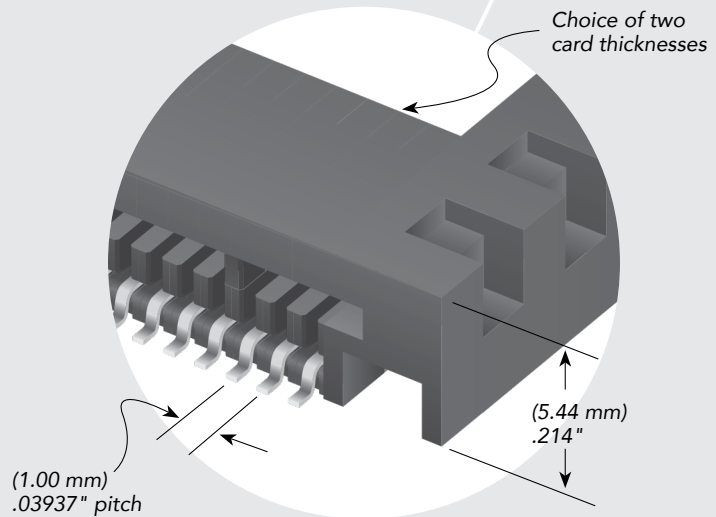
RoHS Compliant:

Yes

Mates with:

(0.80 mm) .031" PCB,

(1.60 mm) .062" PCB



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (20-30)
(0.15 mm) .006" max (40-50)*

*(.004" stencil solution may be available; contact ipg@samtec.com)

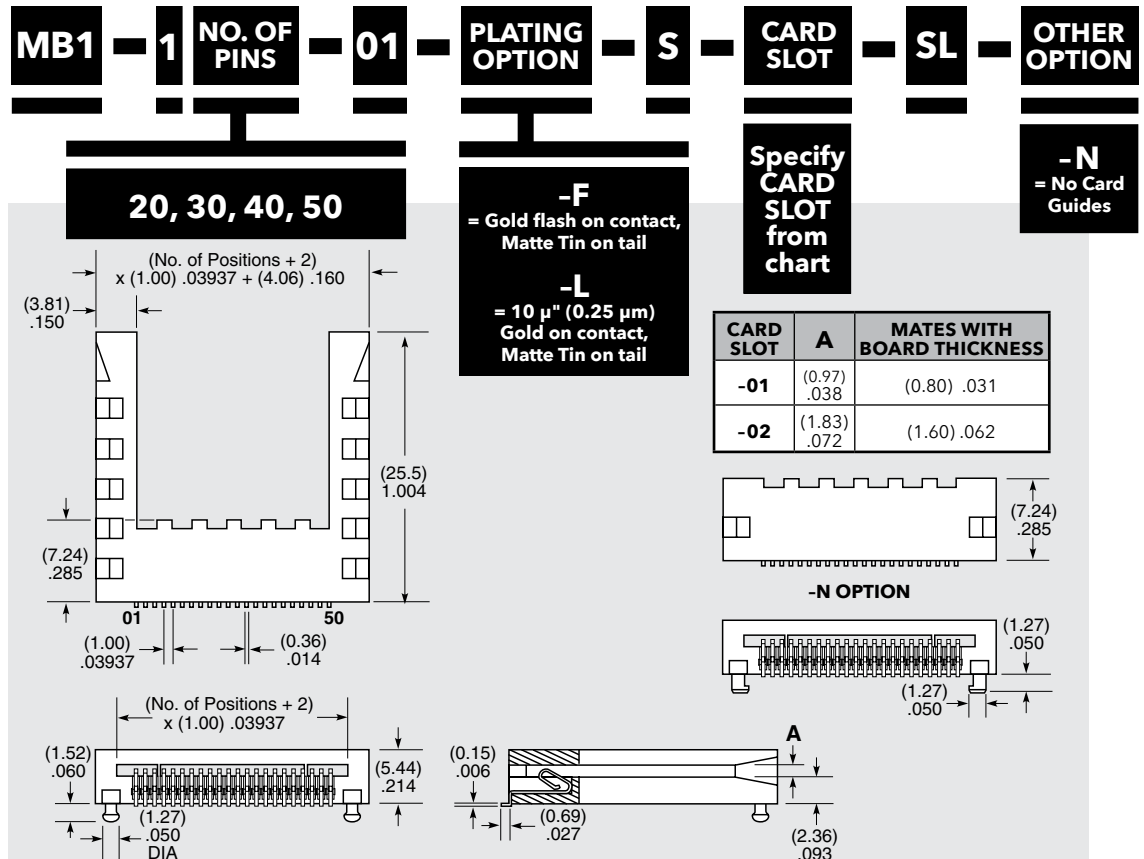
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings



Important Note: Samtec recommends that pads on the mating board be Gold plated.

Note:
Some sizes, styles and options are non-standard, non-returnable.

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Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.